

February 2011

# NC7SZ34 TinyLogic<sup>®</sup> UHS Buffer

## **Features**

- Ultra-High Speed: t<sub>PD</sub> 2.4ns (Typical) into 50pF at 5V V<sub>CC</sub>
- High Output Drive: ±24mA at 3V V<sub>CC</sub>
- Broad V<sub>CC</sub> Operating Range: 1.65V to 5.5V
- Matches Performance of LCX Operated at 3.3V V<sub>CC</sub>
- Power-Down High-Impedance Inputs / Outputs
- Proprietary Noise / EMI Reduction Circuitry
- WLCSP Package

## Description

The NC7SZ34 is a single buffer from Fairchild's Ultra-High Speed (UHS) series of TinyLogic®. The device is fabricated with advanced CMOS technology to achieve ultra-high speed with high output drive, while maintaining low static power dissipation over a broad  $V_{\rm CC}$  operating range of 1.65V to 5.5V  $V_{\rm CC}$ . The inputs and output are high-impedance when  $V_{\rm CC}$  is 0V. Inputs tolerate voltages up to 7V, independent of  $V_{\rm CC}$  operating voltage.

## **Related Resources**

- AN-5055 Portability and Ultra Low Power TinyLogic<sup>®</sup>
- MS-503 Family Characteristics TinyLogic<sup>®</sup> HS/HST and UHS Series

## **Ordering Information**

Part Number	Top Mark	Package	Packing Method
NC7SZ34UCX	KJ	4-Lead, Wafer-Level Chip Scale 0.76x0.76x0.5mm Wafer-Level Chip-Scale Package (WLCSP)	3000 Units on Tape & Reel

# **Pin Configurations**

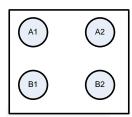


Figure 1. WLCSP (Top View)

## **Pin Definitions**

WLCSP	Name	Description
A1	Α	Input
A2	VCC	Power Supply
B1	GND	Ground
B2	Υ	Output

# **Function Table**

Y= A

Inputs	Output
A	Y
LOW Logic Level	LOW Logic Level
HIGH Logic Level	HIGH Logic Level

## **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Para	ameter	Min.	Max.	Unit
V <sub>CC</sub>	Supply Voltage		-0.5	7.0	V
V <sub>IN</sub>	DC Input Voltage		-0.5	7.0	V
V <sub>OUT</sub>	DC Output Voltage		-0.5	7.0	V
I <sub>IK</sub>	DC Input Diode Current	V <sub>IN</sub> < -0.5V		-50	mA
I <sub>OK</sub>	DC Output Diode Current	V <sub>OUT</sub> < -0.5V		-50	mA
I <sub>OUT</sub>	DC Output Current			±50	mA
I <sub>CC</sub> or I <sub>GND</sub>	DC V <sub>CC</sub> or Ground Current			±50	mA
T <sub>STG</sub>	Storage Temperature Range		-65	+150	°C
TJ	Junction Temperature Under B	ias		+150	°C
TL	Junction Lead Temperature (So	oldering, 10 Seconds)		+260	°C
P <sub>D</sub>	Power Dissipation at +85°C			200	mW
ESD.	Human Body Model, JEDEC:JE	SD22-A114		4000	M
ESD	Charge Device Model, JEDEC:	JESD22-C101		2000	V

# **Recommended Operating Conditions**

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Conditions	Min.	Max.	Unit
V	Supply Voltage Operating		1.65	5.50	V
V <sub>CC</sub>	Supply Voltage Data Retention		1.5	5.5	]
$V_{IN}$	Input Voltage		0	5.5	V
V <sub>OUT</sub>	Output Voltage		0	V <sub>CC</sub>	V
T <sub>A</sub>	Operating Temperature		-40	+85	°C
		V <sub>CC</sub> at 1.8V, 2.5V ±0.2V	0	20	
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Times	V <sub>CC</sub> at 3.3V ±0.3V	0	10	ns/V
		V <sub>CC</sub> at 5.0V ±0.5V	0	5	
$\theta_{JA}$	Thermal Resistance			80	°C/W

### Note:

1. Unused inputs must be held HIGH or LOW. They may not float.

## **DC Electrical Characteristics**

Comple al	Danamatan	V	O a maliti a ma		T <sub>A</sub> =25°C	;	T <sub>A</sub> =-40	to 85°C	11
Symbol	Parameter	V <sub>cc</sub>	Conditions	Min.	Тур.	Max.	Min.	Max.	Unit
.,	HIGH Level	1.65 to 1.95		0.65V <sub>CC</sub>			0.65V <sub>CC</sub>		\ , <i>,</i>
$V_{IH}$	Input Voltage	2.30 to 5.50		0.70V <sub>CC</sub>			0.70V <sub>CC</sub>		V
\/	LOW Level	1.65 to 1.95				0.35V <sub>CC</sub>		0.35V <sub>CC</sub>	V
$V_{IL}$	Input Voltage	2.30 to 5.50				0.30V <sub>CC</sub>		0.30V <sub>CC</sub>	\ \
		1.65		1.55	1.65				
		1.80		1.70	1.80		1.70		
		2.30	V <sub>IN</sub> =V <sub>IH</sub> , I <sub>OH</sub> = -100μΑ	2.20	2.30		2.20		
		3.00	Τοομπ	2.90	3.00		2.90		
\/	HIGH Level	4.50		4.40	4.50		4.40		V
$V_{OH}$	Output Voltage	1.65	I <sub>OH</sub> =-4mA	1.29	1.52	4	1.29		
		2.30	I <sub>OH</sub> =-8mA	1.90	2.15		1.90		
		3.00	I <sub>OH</sub> =-16mA	2.40	2.80		2.40		
		3.00	I <sub>OH</sub> =-24mA	2.30	2.68		2.30		
		4.50	I <sub>OH</sub> =-32mA	3.80	4.20		3.80		
		1.65			0.00	0.10		0.10	
		1.80			0.00	0.10		0.10	
		2.30	$V_{IN}=V_{IL}$ , $I_{OL}=100\mu A$		0.00	0.10		0.10	
		3.00	10L=100μΑ		0.00	0.10		0.10	
\ /	LOW Level	4.50			0.00	0.10		0.10	V
$V_{OL}$	Output Voltage	1.65	I <sub>OL</sub> =4mA		0.08	0.24		0.24	
		2.30	I <sub>OL</sub> =8mA		0.10	0.30		0.30	
		3.00	I <sub>OL</sub> =16mA		0.15	0.40		0.40	
		3.00	I <sub>OL</sub> =24mA		0.22	0.55		0.55	
		4.50	I <sub>OL</sub> =32mA		0.22	0.55		0.55	
I <sub>IN</sub>	Input Leakage Current	0 to 5.5	$0 \le V_{IN} \le 5.5V$			±1		±10	μΑ
I <sub>OFF</sub>	Power Off Leakage Current	0	V <sub>IN</sub> or V <sub>OUT</sub> =5.5V			1		10	μA
I <sub>cc</sub>	Quiescent Supply Current	1.65 to 5.50	V <sub>IN</sub> =5.5V, GND			1.0		10	μΑ

## **AC Electrical Characteristics**

Symbol	Symbol Parameter		V <sub>cc</sub> Conditions		T <sub>A</sub> =25°C		T <sub>A</sub> =-40 to 85°C		Unit	Figure
				Min.	Тур.	Max.	Min.	Max.	S	
		1.65		2.0	5.3	11.4	2.0	12.0		
		1.80		2.0	4.4	9.5	2.0	10.0		
			$C_L=15pF,$ $R_L=1M\Omega$	0.8	2.9	6.5	0.8	7.0		
t <sub>PLH</sub> , t <sub>PHL</sub>	Propagation Delay	3.3 ±0.3		0.5	2.1	4.5	0.5	4.7	ns	Figure 2 Figure 3
		5.0 ±0.5			0.5	1.8	3.9	0.5	4.1	
		3.3 ±0.3	C <sub>L</sub> =50pF,	1.5	2.9	5.0	1.5	5.2		
		5.0 ±0.5	R <sub>L</sub> =500Ω	0.8	2.4	4.3	0.8	4.5		
C <sub>IN</sub>	Input Capacitance	0.00			2.0				pF	
	Power Dissipation	3.30			12.9				ρE	Figure 4
$C_{PD}$	Capacitance <sup>(2)</sup>	5.00		·	15.6				pF	Figure 4

#### Note:

C<sub>PD</sub> is defined as the value of the internal equivalent capacitance derived from dynamic operating current
consumption (I<sub>CCD</sub>) at no output lading and operating at 50% duty cycle. C<sub>PD</sub> is related to I<sub>CCD</sub> dynamic operating
current by the expression: I<sub>CCD</sub>=(C<sub>PD</sub>)(V<sub>CC</sub>)(f<sub>IN</sub>)+(I<sub>CC</sub>static).

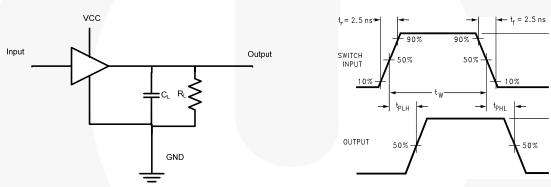


Figure 2. AC Test Circuit

Figure 3. AC Waveforms

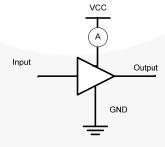
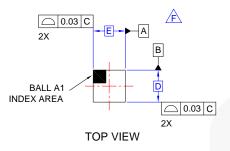


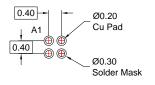
Figure 4. I<sub>CCD</sub> Test Circuit

## Note:

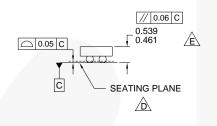
3. Input=AC Waveform;  $t_r=t_f=1.8$ ns; Frequency =10MHz; Duty Cycle =50%.

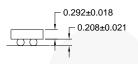
# **Physical Dimensions**





# RECOMMENDED LAND PATTERN (NSMD PAD TYPE)





#### NOTES:

SIDE VIEWS

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCE PER ASME Y14.5M, 1994.
- DATUM C IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
- E.PACKAGE NOMINAL HEIGHT IS 500 MICRONS ±39 MICRONS (461-539 MICRONS).
- F. FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET.
  - G. DRAWING FILNAME: MKT-UC004AFrev1.

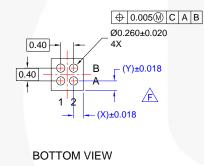


Figure 5. 4-Lead, Wafer-Level Chip Scale 0.76x0.76x0.5mm Wafer-Level Chip-Scale Package (WLCSP)

Product	D	E	X	Υ
NC7SZ34UCX	0.76 +/-0.030	0.76 +/-0.030	0.18	0.18

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings: <a href="http://www.fairchildsemi.com/packaging/">http://www.fairchildsemi.com/packaging/</a>.

## **Tape and Reel Specifications**

Please visit Fairchild Semiconductor's online packaging area for the most recent tape and reel specifications: <a href="http://www.fairchildsemi.com/packaging/SOT23-5L">http://www.fairchildsemi.com/packaging/SOT23-5L</a> tr.pdf.

Package Designator	Tape Section	Cavity Number	<b>Cavity Status</b>	Cover Type Status	
	Leader (Start End)	125 (Typical)	Empty	Sealed	
UCX	Carrier	3000	Filled	Sealed	
	Trailer (Hub End)	75 (Typical)	Empty	Sealed	





#### **TRADEMARKS**

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

intended to be an exhaustive list of all

AccuPower™ F-PF
Auto-SPM™ FRF
AX-CAP™\* Glob
Build it Now™ Gree
CorePCWER™ Groe
COREPCWER™ GTO
CTL™ Intel
Current Transfer Logic™ ISO
DEUXPEED® Meg
Dual Cool™ MIC
EcoSPARK® Micr
ESBC™ Micr

Fairchild®
Fairchild Semiconductor®
FACT Quiet Series™
FACT®
FAST®
FastvCore™

FETBench™ FlashWriter®\* FPS™ F-PFS™ FRFET®

Global Power Resource<sup>s</sup>
Green FPSTM
Green FPSTM e-SeriesTM

Gmax<sup>TM</sup>
GTO<sup>TM</sup>
IntelliMAX<sup>TM</sup>
ISOPLANAR<sup>TM</sup>
MegaBuck<sup>TM</sup>
MICROCOUPLER<sup>TM</sup>

MicroECOOFLER
MicroPak™
MicroPak2™
MillerDrive™
MotionMax™
Motion-SPM™
mVVSaver™
OptoHiT™

OPTOPLANAR® ® PDP SPM™

OPTOLOGIC®

Power-SPM™ PowerTrench® PowerXS™

Programmable Active Droop™ QFET®

QS™ Quiet Series™ RapidConfigure™

Saving our world, 1mVVVV/kVV at a time™ SignalVVise™

Signalivise M
SmartMax M
SMART START M
SPM®
STEALTH M
SUpported T®

STEALTH™
SuperFET®
SuperSOT™8
SuperSOT™8
SuperSOT™8
SuperMOS®
SyncFET™
Sync-Lock™
SYSTEM®\*

The Power Franchise®

The Right Technology for Your Success™

p wer

TinyBoost™
TinyBuck™
TinyCalc™
TinyCogic®
TINYOPTO™
TinyPower™
TinyPower™
TinyPWM™
TinyWire™
TripAult Detect™
TRUECURRENT®
µSerDes™

SerDes"
UHC
Ultra FRFET™
UniFET™
VCX™
VisualMax™
XS™

#### DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN, FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

#### LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

#### As used herein:

- Life support devices or systems are devices or systems which, (a)
  are intended for surgical implant into the body or (b) support or
  sustain life, and (c) whose failure to perform when properly used in
  accordance with instructions for use provided in the labeling, can be
  reasonably expected to result in a significant injury of the user.
- A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

### ANTI-COUNTERFEITING POLICY

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, www.fairchildsemi.com, under Sales Support.

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufacturers of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed applications, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handling and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address any warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

#### PRODUCT STATUS DEFINITIONS

#### **Definition of Terms**

Datasheet Identification	Product Status	Definition
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

Rev. 153

<sup>\*</sup> Trademarks of System General Corporation, used under license by Fairchild Semiconductor.

